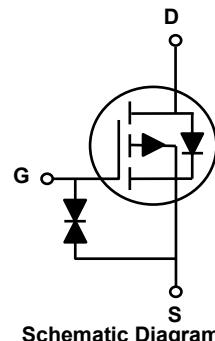
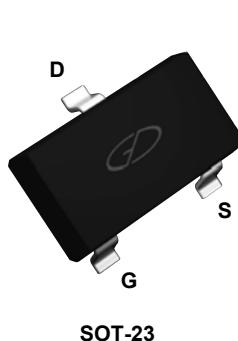


### Main Product Characteristics

BV <sub>DSS</sub>	-25V
R <sub>DS(ON)</sub>	640mΩ
I <sub>D</sub>	-0.85A



### Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



### Description

The GSFC02501 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

### Absolute Maximum Ratings ( $T_J=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	V <sub>DS</sub>	-25	V
Gate-Source Voltage	V <sub>GS</sub>	±8	V
Drain Current-Continuous ( $T_A=25^\circ\text{C}$ ) <sup>1,3</sup>	I <sub>D</sub>	-0.85	A
Drain Current-Continuous ( $T_A=70^\circ\text{C}$ ) <sup>1,3</sup>		-0.68	
Drain Current-Pulsed <sup>2</sup>	I <sub>DM</sub>	-2.1	A
Power Dissipation ( $T_A=25^\circ\text{C}$ )	P <sub>D</sub>	0.69	W
Power Dissipation ( $T_A=70^\circ\text{C}$ )		0.44	W
Thermal Resistance, Junction-to-Ambient <sup>1</sup>	R <sub>θJA</sub>	180	°C/W
Operating Junction Temperature Range	T <sub>J</sub>	-55 To +150	°C
Storage Temperature Range	T <sub>STG</sub>	-55 To +150	°C

**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On / Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-25	-	-	V
Drain-Source Leakage Current	$I_{\text{DS}(\text{SS})}$	$V_{\text{DS}}=-16\text{V}, V_{\text{GS}}=0\text{V}$	-	-	-1	$\mu\text{A}$
Gate-Source Leakage Current	$I_{\text{GS}(\text{SS})}$	$V_{\text{GS}}=\pm 12\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm 10$	$\mu\text{A}$
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-0.55\text{A}$	-	530	640	$\text{m}\Omega$
		$V_{\text{GS}}=-2.5\text{V}, I_{\text{D}}=-0.45\text{A}$	-	730	950	
		$V_{\text{GS}}=-1.8\text{V}, I_{\text{D}}=-0.35\text{A}$	-	1300	1950	
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=-250\mu\text{A}$	-0.5	-	-1	V
Forward Transconductance	$g_{\text{fs}}$	$V_{\text{DS}}=-5\text{V}, I_{\text{D}}=-0.55\text{A}$	-	1	-	S
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge <sup>3,4</sup>	$Q_g$	$V_{\text{GS}}=-2.5\text{V}, V_{\text{DS}}=-10\text{V}, I_{\text{D}}=-1\text{A}$	-	0.53	-	nC
Total Gate Charge <sup>3,4</sup>	$Q_g$	$V_{\text{DS}}=-10\text{V}, I_{\text{D}}=-1\text{A}$ $V_{\text{GS}}=-4.5\text{V}$	-	0.8	-	nC
Gate-Source Charge <sup>3,4</sup>	$Q_{\text{gs}}$		-	0.2	-	
Gate-Drain Charge <sup>3,4</sup>	$Q_{\text{gd}}$		-	0.2	-	
Turn-On Delay Time <sup>3,4</sup>	$t_{\text{d}(\text{on})}$	$V_{\text{DS}}=-10\text{V}, R_{\text{G}}=3\Omega$ $V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-1.33\text{A}$	-	400	-	nS
Rise Time <sup>3,4</sup>	$t_r$		-	60	-	
Turn-Off Delay Time <sup>3,4</sup>	$t_{\text{d}(\text{off})}$		-	20	-	
Fall Time <sup>3,4</sup>	$t_f$		-	800	-	
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=-10\text{V}, V_{\text{GS}}=0\text{V}, F=1\text{MHz}$	-	58	-	pF
Output Capacitance	$C_{\text{oss}}$		-	5.7	-	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	4.4	-	
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Diode Forward Voltage	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_{\text{SD}}=-1\text{A}$	-	-	-1.1	V
Reverse Recovery Time	$t_{\text{rr}}$	$I_F=-1\text{A},$ $\text{di}/\text{dt}=100\text{A}/\mu\text{s}$	-	9.2	-	nS
Reverse Recovery Charge	$Q_{\text{rr}}$	$I_F=-1\text{A},$ $\text{di}/\text{dt}=100\text{A}/\mu\text{s}$	-	0.8	-	nC

Notes:

- The value of  $R_{\theta_{\text{JA}}}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ\text{C}$ . The value in any given application depends on the user's specific board design.
- Repetitive rating, pulse width limited by junction temperature.
- The current rating is based on the  $t<10\text{s}$  junction to ambient thermal resistance rating.

## Typical Electrical and Thermal Characteristic Curves

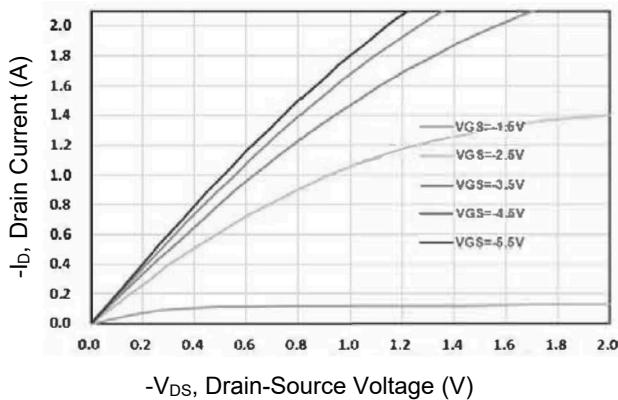


Figure 1. Output Characteristics

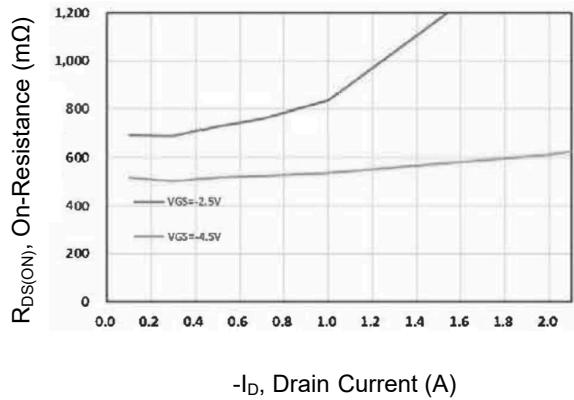


Figure 2. On-Resistance vs.  $I_D$

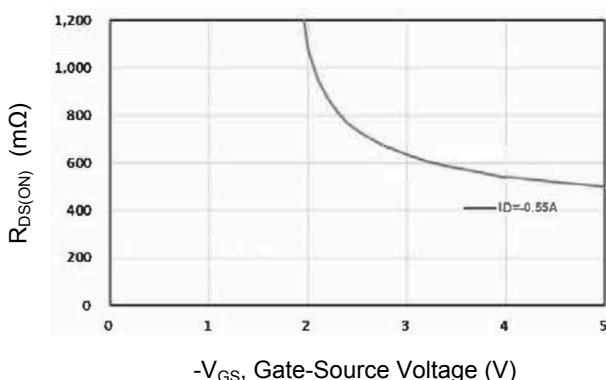


Figure 3. Power Dissipation

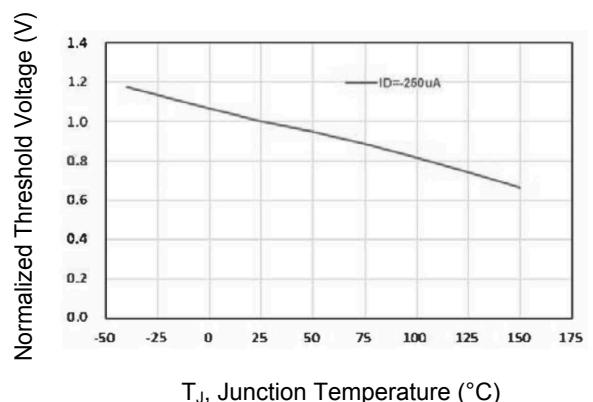


Figure 4. Gate Threshold Voltage

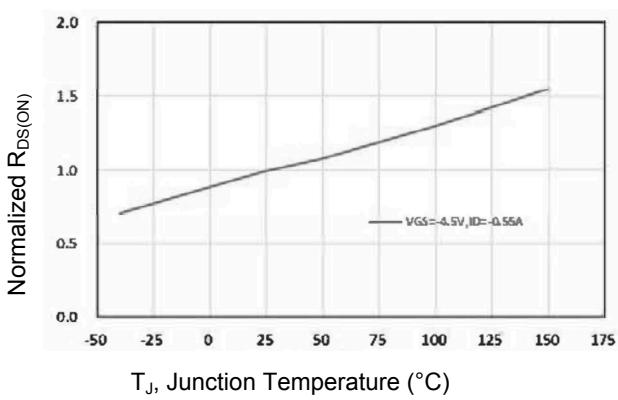


Figure 5. Drain-Source On Resistance

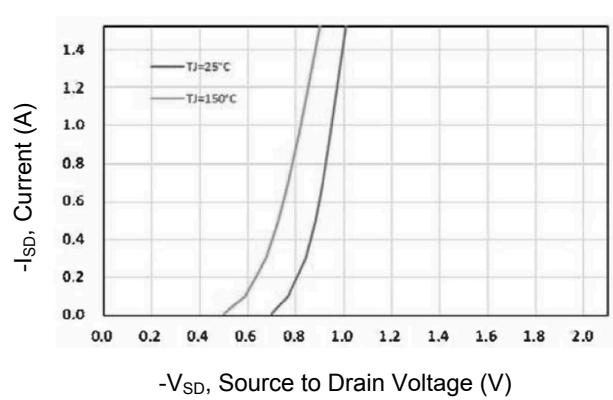
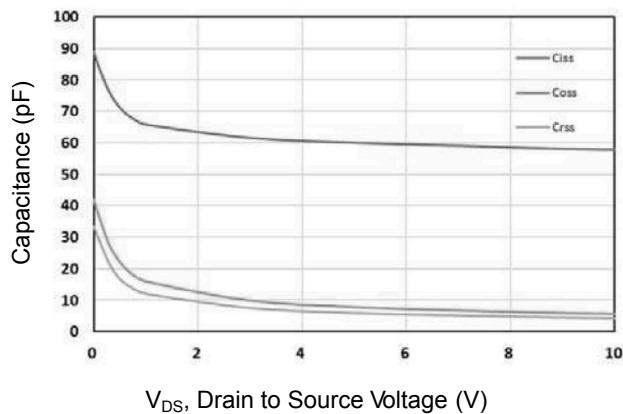
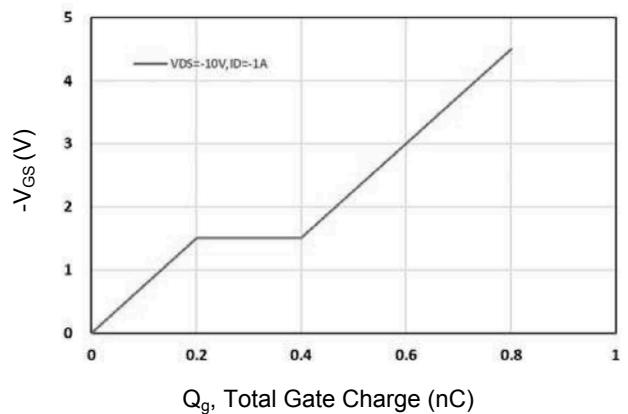


Figure 6. Source-Drain Diode Forward

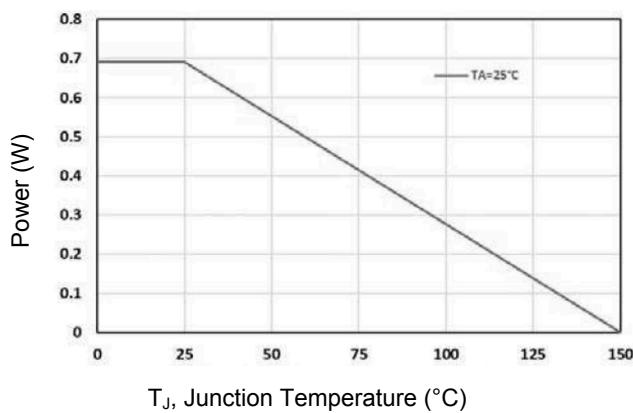
## Typical Electrical and Thermal Characteristic Curves



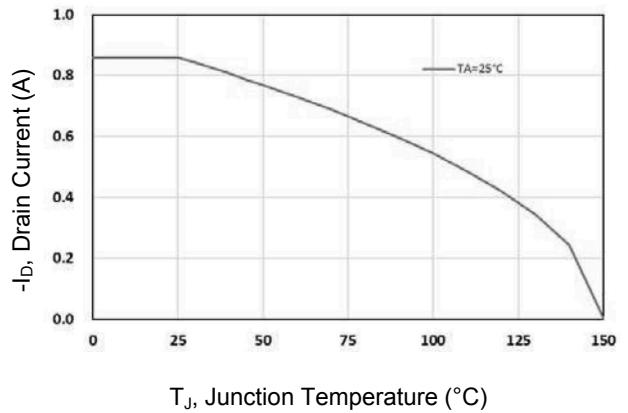
**Figure 7. Capacitance Characteristics**



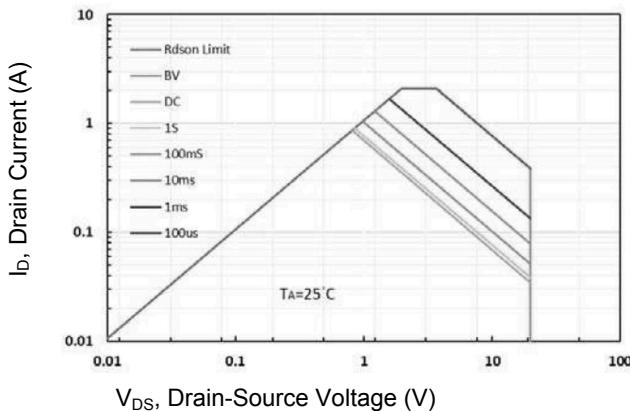
**Figure 8. Gate Charge Characteristics**



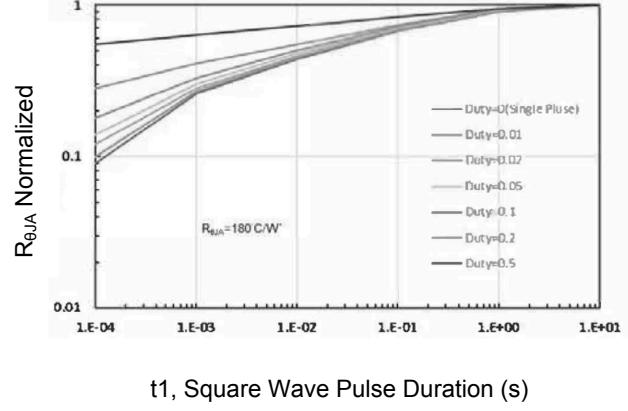
**Figure 9. Power Dissipation**



**Figure 10. Drain Current**

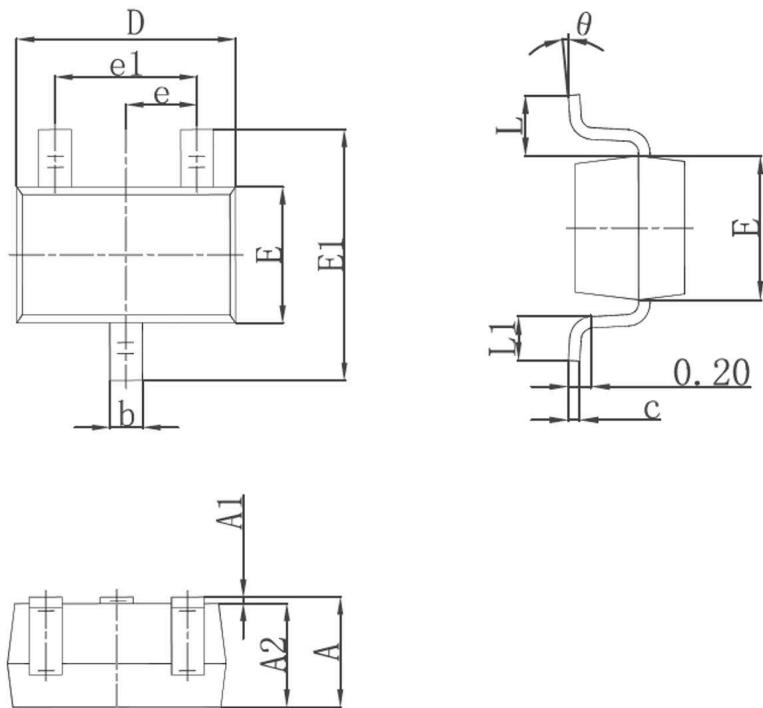


**Figure 11. Safe Operating Area**



**Figure 12.  $R_{\theta JA}$  Transient Thermal Impedance**

### Package Outline Dimensions (SOT-23)



Symbol	Dimensions in Millimeters		Dimensions in Inches	
	Min	Max	Min	Max
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.200	0.400	0.008	0.016
c	0.080	0.150	0.003	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.450	0.085	0.096
e	0.650 TYP		0.026 TYP	
e1	1.200	1.400	0.047	0.055
L	0.525 REF		0.021 REF	
L1	0.260	0.460	0.010	0.018
θ	0°	8°	0°	8°